



Material Content Data Sheet



Sales Product Name		BSC360N15NS3 G		Issued		20. July 2018		
MA#		MA001644286						
Package		PG-TDSON-8-39		Weight*		112.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.357	2.09	2.09	20872	20872
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		431	
	non noble metal	copper	7440-50-8	48.649	43.09	43.14	430851	431411
	non noble metal	copper	7440-50-8	0.072	0.06	0.06	641	641
wire	non noble metal	copper	7440-50-8	0.072	0.06	0.06	641	641
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		722	
	plastics	epoxy resin	-	6.441	5.70		57042	
	inorganic material	silicondioxide	60676-86-0	34.243	30.33	36.10	303264	361028
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13462	13462
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1403	1403
solder	non noble metal	tin	7440-31-5	0.045	0.04		398	
	noble metal	silver	7440-22-4	0.056	0.05		497	
	non noble metal	lead	7439-92-1	2.146	1.90	1.99	19004	19899
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1329	
	non noble metal	copper	7440-50-8	16.910	14.98	15.13	149760	151284
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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